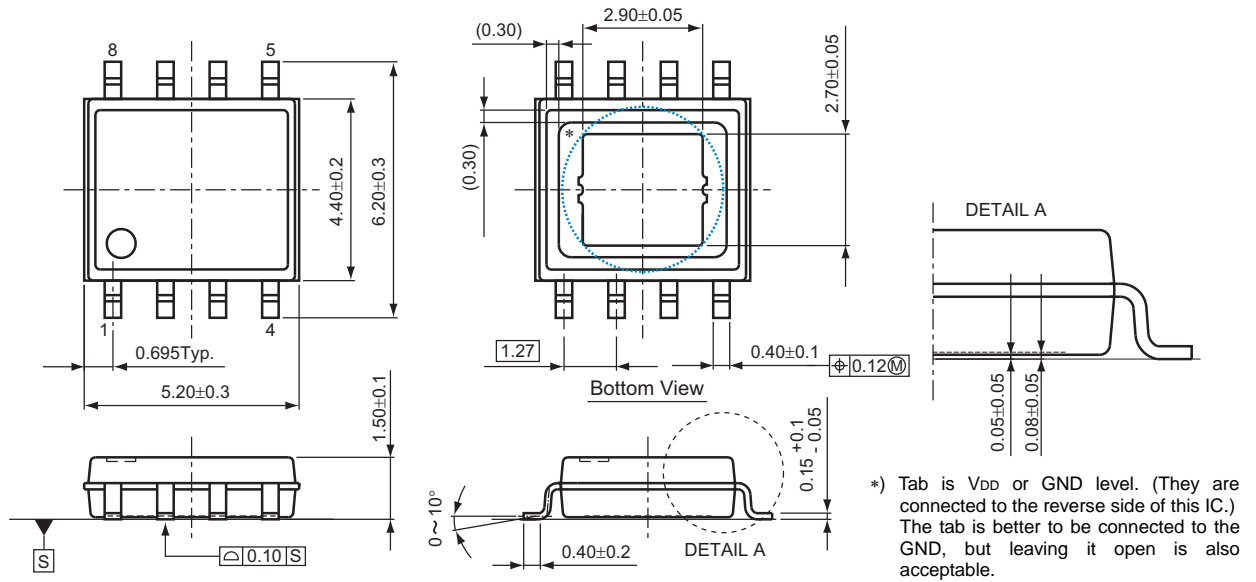


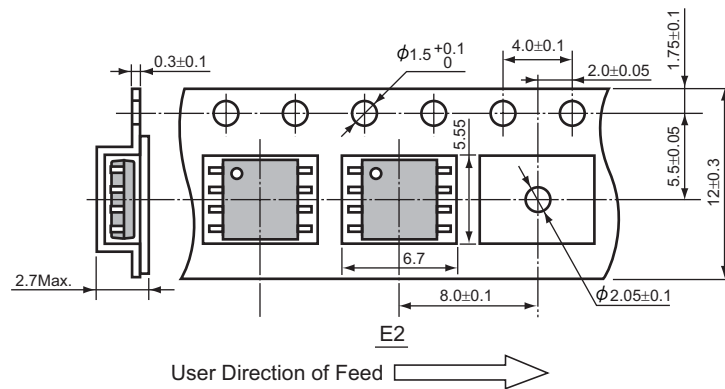
• HSOP-8E

Unit: mm

PACKAGE DIMENSIONS

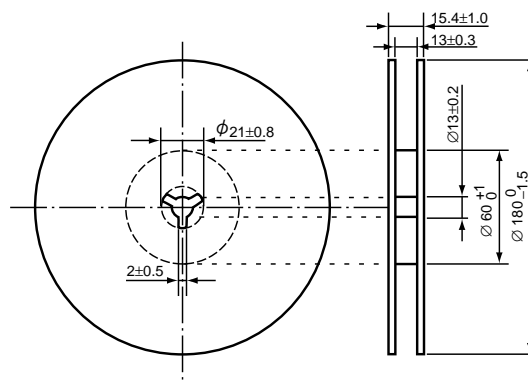


TAPING SPECIFICATION



TAPING REEL DIMENSIONS REUSE REEL (EIAJ-RRM-12Bc)

(1reel=1,000pcs)



POWER DISSIPATION (HSOP-8E)

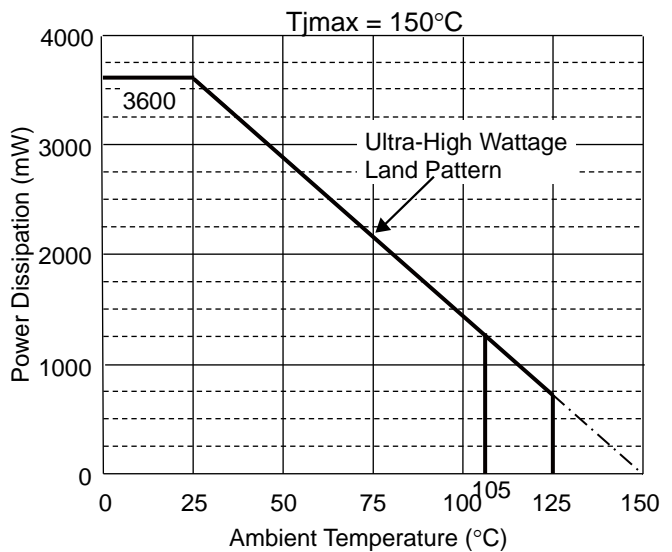
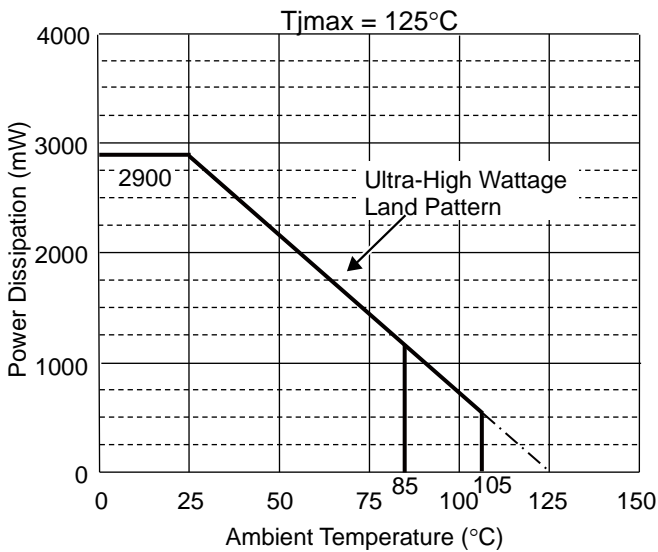
This specification is at mounted on board. Power Dissipation (P_D) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

Measurement Conditions

	Ultra-High Wattage Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass Cloth Epoxy Plastic (4 layers)
Board Dimensions	76.2mm × 114.3mm × 0.8mm
Copper Ratio	Outer Layers (First and Fourth Layers): Approx. 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square
Through-holes	φ0.4mm × 21pcs

Measurement Results ($T_a=25^\circ\text{C}$)

	Ultra-High Wattage Land Pattern
Power Dissipation	2900 mW ($T_{jmax} = 125^\circ\text{C}$) 3600 mW ($T_{jmax} = 150^\circ\text{C}$)
Thermal Resistance	$\theta_{ja} = 35^\circ\text{C/W}$ $\theta_{jc} = 10^\circ\text{C/W}$



RECOMMENDED LAND PATTERN

